

ABSTRACT OF THE DISCLOSURE

A method for applying a thin-walled, flat substrate, such as a wafer, to an assembly carrier with a preferably level protective layer, for example a wax. With respect to the protective layer, the substrate is arranged at a spacing and is curved in a convex manner. The substrate is contacted with the protective layer. Finally, the substrate is laid over the entire protective layer from the contact point towards the edge of the substrate.